

E

D

C

B

A

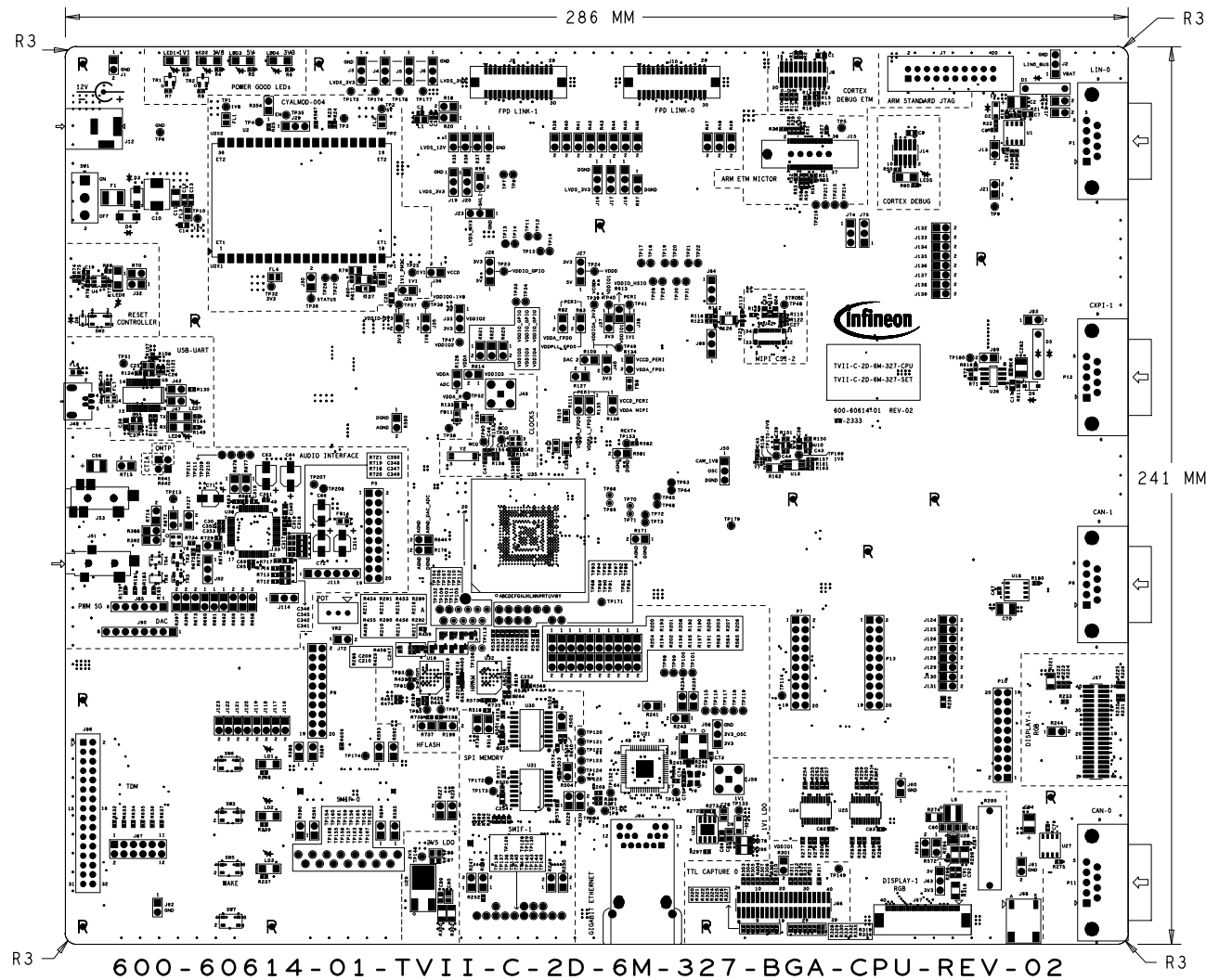
E

D

C

B

A



600-60614-01-TVII-C-2D-6M-327-BGA-CPU-REV-02
600-60614-01-TVII-C-2D-6M-327-BGA-SET-REV-02

PRIMARY ASSEMBLY

LAYERS	WIDTH	90 OHM		100 OHM	
		WIDTH	SPACING	WIDTH	SPACING
TOP	7	5	5.35	5	8
GND 1	-	-	-	-	-
SIGNAL 1	7	-	-	-	-
POWER	-	-	-	-	-
GND 2	-	-	-	-	-
BOTTOM	7	5	5.35	5	8

NOTES:(UNLESS OTHERWISE SPECIFIED)

- RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
- MATERIAL:
 - IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
 - USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
 - OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
- DRILLING:
 - DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 to 1. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
 - TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
- PLATING:
 - COPPER PLATING IN THRU-HOLES .001 min.
- MARKING:
 - SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
 - FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN NON-CONDUCTIVE EPOXY INK.
- FINAL FABRICATION:
 - SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDRMASK COLOR **GREEN**
- FINISH:
 - SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
 - NICKEL THICKNESS: 100-200 MICROINCHES.
 - GOLD THICKNESS: 3-10 MICROINCHES.
- BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPLIANT SYMBOL.
- MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
- MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
- TESTING:
 - FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
 - T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

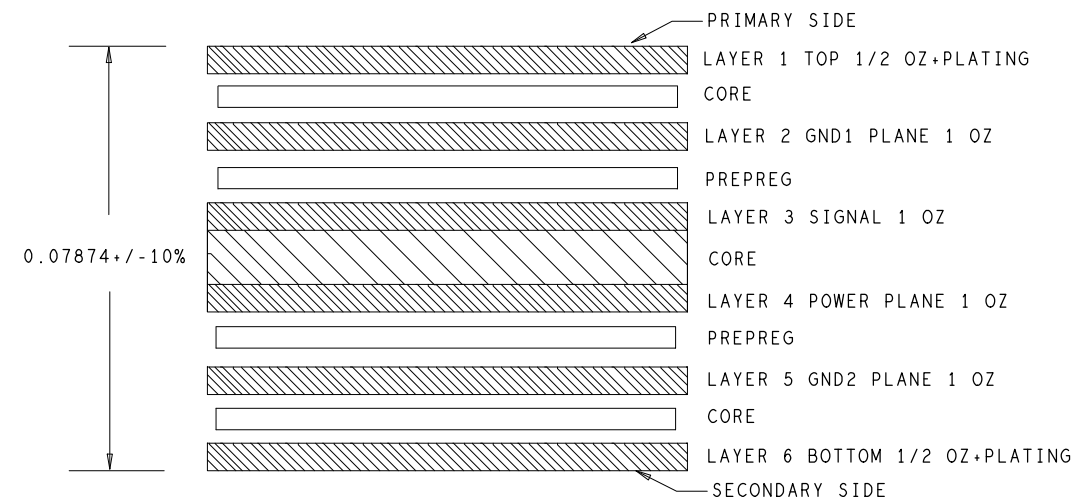
REVISIONS



S.No	DESCRIPTION	DATE	APPROVED
01	INITIAL RELEASE	14/01/20	SPPD
01	REV-A	05/04/20	SPPD
02	REV-B	12/06/21	AVEN
03	REV-01	01/09/21	AVEN
04	REV-02	18/08/23	MERWIN

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	8.0	+3.0/-3.0	PLATED	121
.	8.0	+3.0/-3.0	PLATED	21
.	8.0	+3.0/-3.0	PLATED	592
.	10.0	+3.0/-3.0	PLATED	1150
.	21.0	+3.0/-3.0	PLATED	2
.	27.56	+3.0/-3.0	PLATED	3
A	32.0	+3.0/-3.0	PLATED	5
.	35.0	+3.0/-3.0	PLATED	5
.	36.0	+3.0/-3.0	PLATED	2
A	40.0	+3.0/-3.0	PLATED	12
.	40.0	+3.0/-3.0	PLATED	183
.	40.0	+3.0/-3.0	PLATED	20
D	40.0	+3.0/-3.0	PLATED	516
C	43.3	+3.0/-3.0	PLATED	4
D	43.3	+3.0/-3.0	PLATED	36
E	43.3	+3.0/-3.0	PLATED	2
F	44.0	+3.0/-3.0	PLATED	36
.	45.0	+3.0/-3.0	PLATED	4
H	56.0	+3.0/-3.0	PLATED	8
I	62.0	+3.0/-3.0	PLATED	2
J	72.0	+3.0/-3.0	PLATED	3
K	120.0	+3.0/-3.0	PLATED	8
.	31.5	+3.0/-3.0	NON-PLATED	2
M	44.5	+3.0/-3.0	NON-PLATED	2
N	64.2	+3.0/-3.0	NON-PLATED	2
O	70.0	+3.0/-3.0	NON-PLATED	2
P	74.8	+3.0/-3.0	NON-PLATED	2
Q	94.0	+4.0/-4.0	NON-PLATED	1
R	128.0	+4.0/-4.0	NON-PLATED	14
S	128.0	+4.0/-4.0	NON-PLATED	2
.	74.0x28.0	+4.0/-4.0	PLATED	2
B	120.0x30.0	+4.0/-4.0	PLATED	1
.	120.0x30.0	+4.0/-4.0	PLATED	1
B	140.0x40.0	+4.0/-4.0	PLATED	1



UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE		<div></div> <div>TVII-C-2D-6M-327-BGA</div> <div>CPU-BOARD_REV-02</div>									
DIMENSIONS ARE IN INCHES		DRAWN		RASB						18/08/23					
TOLERANCES ON: ANGLES +/- .2		CHECKED		MERWIN						18/08/23					
2 PL DECIMALS +/- .010		ENGRG													
3 PL DECIMALS +/- .005		ISSUED						<div>SCALE: 1/1</div> <div>SHEET:</div>							
THIRD ANGLE PROJECTIONS 															
CYPRESS PROPRIETARY															
THIS DOCUMENT CONTAINS CONFIDENTIAL, PROPRIETARY INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY.															
DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS.								SIZE		FSCM NO		DWG NO		REV	
								C				620-60614-01		02	